

N-channel 650 V, 0.250 Ω , 15 A TO-220, TO-220FP
second generation MDmesh™ Power MOSFET

Features

Order codes	V_{DSS} @ T_{jmax}	$R_{DS(on)}$ max.	I_D
STP20NM65N	710 V	0.270 Ω	15 A
STF20NM65N			

- 100 % avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

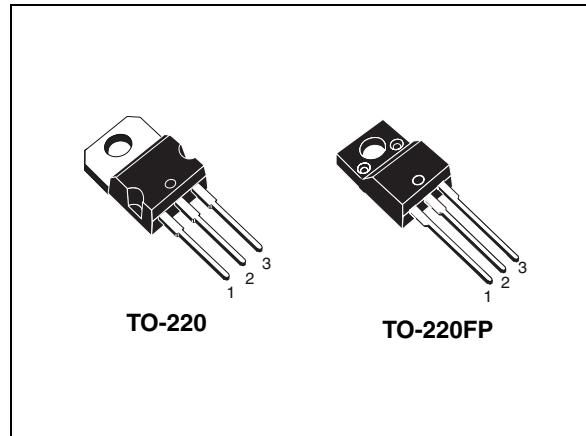


Figure 1. Internal schematic diagram

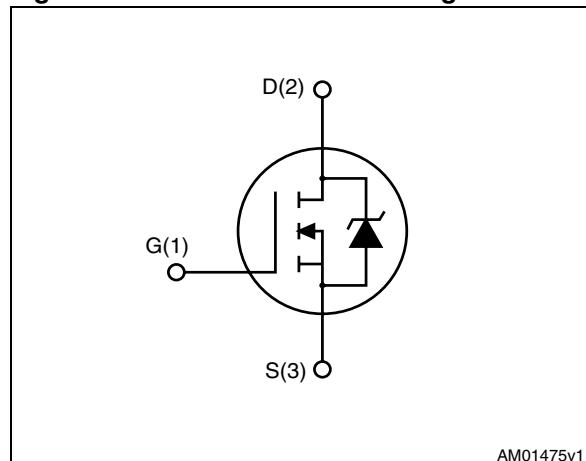


Table 1. Device summary

Order codes	Marking	Package	Packaging
STP20NM65N	20NM65N	TO-220	Tubes
STF20NM65N	20NM65N	TO-220FP	Tubes

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220	TO-220FP	
V_{DS}	Drain source voltage	650		V
V_{GS}	Gate source voltage	± 25		V
I_D	Drain current continuous $T_C = 25^\circ\text{C}$	15	15 ⁽¹⁾	A
I_D	Drain current continuous $T_C = 100^\circ\text{C}$	9.45		A
$I_{DM}^{(2)}$	Drain current pulsed	60		A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	125	30	W
$dv/dt^{(3)}$	Peak diode recovery voltage slope	15		V/ns
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heatsink ($t=1\text{ s}$; $T_C = 25^\circ\text{C}$)		2500	V
T_{stg} T_J	Storage temperature Max. operating junction temperature	-55 to 150 150		$^\circ\text{C}$

1. Limited only by maximum temperature allowed.
2. Pulse width limited by safe operating area.
3. $I_{SD} \leq 15\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, V_{DS} peak $\leq V_{(BR)DSS}$, $V_{DD} = 80\% V_{(BR)DSS}$.

Table 3. Thermal data

Symbol	Parameters	Value		Unit
		TO-220	TO-220FP	
R_{thjc}	Thermal resistance junction-case max.	1	4.17	$^\circ\text{C/W}$
R_{thja}	Thermal resistance junction-ambient max.	62.50		$^\circ\text{C/W}$
T_J	Max. lead temperature for soldering purposes	300		$^\circ\text{C}$

Table 4. Avalanche characteristics

Symbol	Parameters	Value	Unit
I_{AS}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_J max)	4	A
E_{AS}	Single pulse avalanche energy (starting $T_J = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	115	mJ

2 Electrical characteristics

($T_C = 25^\circ\text{C}$ unless otherwise specified).

Table 5. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	650			V
I_{DSS}	Zero gate voltage drain current ($V_{GS}=0$)	$V_{DS} = \text{max rating}$ $V_{DS} = \text{max rating} @ 125^\circ\text{C}$			1 100	μA μA
I_{GSS}	Gate body leakage ($V_{DS}=0$)	$V_{GS} = \pm 25 \text{ V}, V_{DS}=0$			100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$I_D = 250 \mu\text{A},$ $V_{GS} = V_{DS}$	2	3	4	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$I_D=7.5 \text{ A}, V_{GS}=10 \text{ V}$		0.250	0.270	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 50 \text{ V}, f = 1\text{MHz}, V_{GS} = 0$	-	1280	-	pF
C_{oss}	Output capacitance			110		pF
C_{rss}	Reverse capacitance			10		pF
$C_{oss \text{ eq}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } V_{GS} = 0$	-	260	-	pF
R_G	Intrinsic gate resistance	$f = 1\text{MHz}$ open drain	-	4.8	-	Ω
Q_g	Total gate charge	$V_{DD} = 520 \text{ V}, I_D = 15 \text{ A},$ $V_{GS} = 10 \text{ V}$	-	44	-	nC
Q_{gs}	Gate source charge			8		nC
Q_{gd}	Gate-drain charge			22		nC

1. $C_{oss \text{ eq}}$: defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80 % V_{DSS} .

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 325 \text{ V}, I_D=7.5 \text{ A}$ $R_g=4.7 \Omega$ $V_{GS}=10 \text{ V}$	-	15	-	ns
t_r	Rise time			13.5		ns
$t_{d(off)}$	Turn-off-delay time	$V_{DD} = 325 \text{ V}, I_D=7.5 \text{ A}$ $R_g=4.7 \Omega$ $V_{GS}=10 \text{ V}$	-	75	-	ns
t_f	Fall time			21		ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}^{(1)}$	Source drain current Source drain current (pulsed)		-		15 60	A A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 15 \text{ A}, V_{GS} = 0$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 15 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$ (see)	-	455	ns nC A	
Q_{rr}	Reverse recovery charge			5.5		
I_{RRM}	Reverse recovery current			24.5		
t_{rr}	Reverse recovery time	$I_{SD} = 15 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}, T_j = 150^\circ\text{C}$	-	710	ns nC A	
Q_{rr}	Reverse recovery charge			8		
I_{RRM}	Reverse recovery current			24		

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5 %.

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220

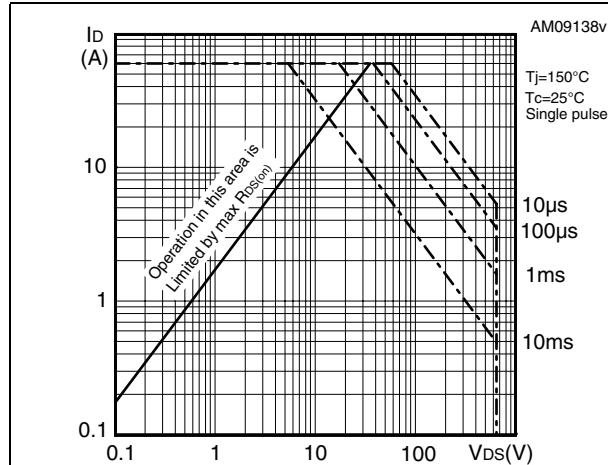


Figure 3. Thermal impedance for TO-220

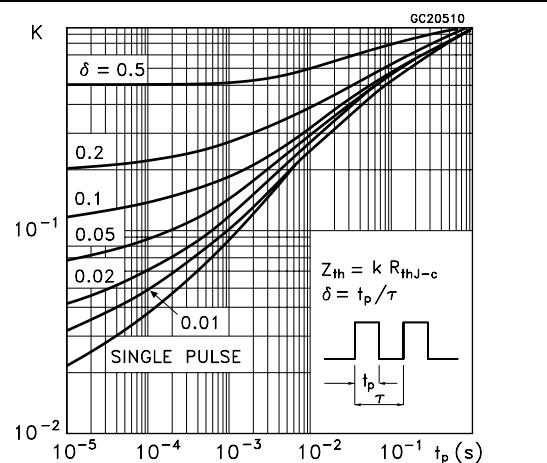


Figure 4. Safe operating area for TO-220FP

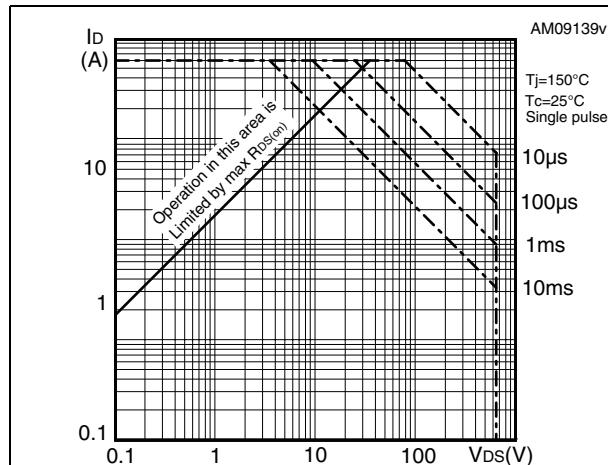


Figure 5. Thermal impedance for TO-220FP

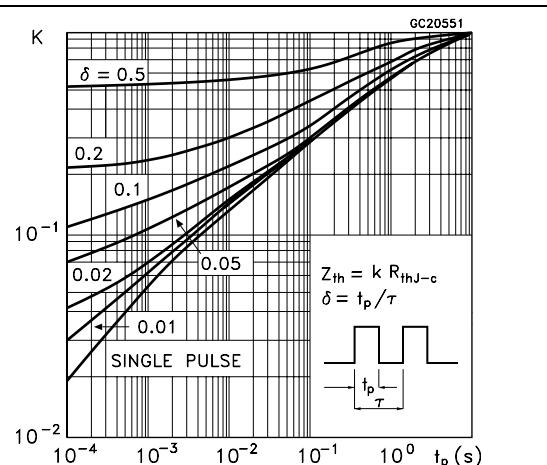


Figure 6. Output characteristics

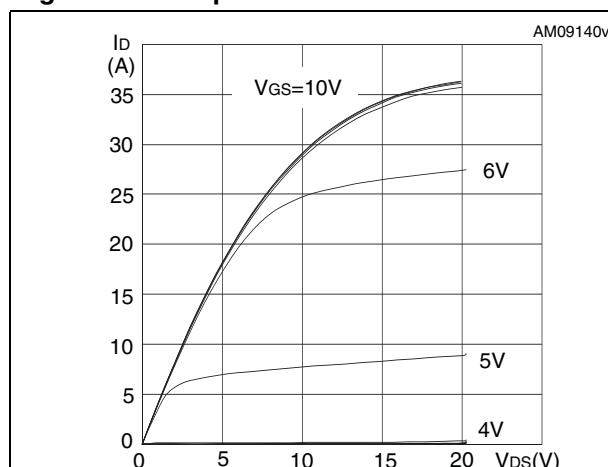


Figure 7. Transfer characteristics

